

**OptiMOS®-P2 Power-Transistor**

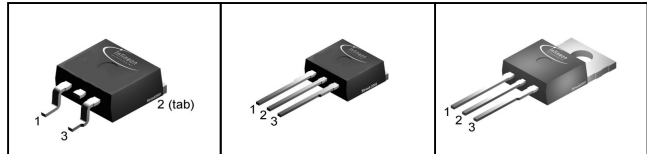
**Product Summary**

|                            |     |            |
|----------------------------|-----|------------|
| $V_{DS}$                   | -40 | V          |
| $R_{DS(on)}$ (SMD Version) | 7.4 | m $\Omega$ |
| $I_D$                      | -80 | A          |

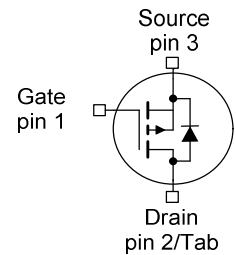
**Features**

- P-channel - Normal Level - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (RoHS compliant)
- 100% Avalanche tested

PG-TO263-3-2    PG-TO262-3-1    PG-TO220-3-1



| Type          | Package      | Marking |
|---------------|--------------|---------|
| IPB80P04P4-07 | PG-TO263-3-2 | 4P0407  |
| IPI80P04P4-07 | PG-TO262-3-1 | 4P0407  |
| IPP80P04P4-07 | PG-TO220-3-1 | 4P0407  |


**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

| Parameter                              | Symbol         | Conditions   | Value        | Unit |
|--|----------------|--|--------------|------|
| Continuous drain current <sup>1)</sup> | $I_D$          | $T_C=25\text{ °C}$ ,<br>$V_{GS}=-10\text{V}$       | -80          | A    |
|  |                | $T_C=100\text{ °C}$ ,<br>$V_{GS}=-10\text{V}^{2)}$ | 62           |      |
| Pulsed drain current <sup>2)</sup>     | $I_{D,pulse}$  | $T_C=25\text{ °C}$                                 | -320         |      |
| Avalanche energy, single pulse         | $E_{AS}$       | $I_D=-40\text{A}$                                  | 31           | mJ   |
| Avalanche current, single pulse        | $I_{AS}$       | -  | -80          | A    |
| Gate source voltage                    | $V_{GS}$       | -  | $\pm 20$     | V    |
| Power dissipation                      | $P_{tot}$      | $T_C=25\text{ °C}$                                 | 88           | W    |
| Operating and storage temperature      | $T_j, T_{stg}$ | -  | -55 ... +175 | °C   |
| IEC climatic category; DIN IEC 68-1    | -              | -  | 55/175/56    |      |

| Parameter                                      | Symbol     | Conditions                                   | Values |      |      | Unit |
|--|------------|--|--------|------|------|------|
|  |            |  | min.   | typ. | max. |      |
| <b>Thermal characteristics<sup>2)</sup></b>    |            |  |        |      |      |      |
| Thermal resistance, junction - case            | $R_{thJC}$ | -  | -      | -    | 1.7  | K/W  |
| Thermal resistance, junction - ambient, leaded | $R_{thJA}$ | -  | -      | -    | 62   |      |
| SMD version, device on PCB                     | $R_{thJA}$ | minimal footprint                            | -      | -    | 62   |      |
|  |            | 6 cm <sup>2</sup> cooling area <sup>3)</sup> | -      | -    | 40   |      |

**Electrical characteristics**, at  $T_j=25\text{ }^\circ\text{C}$ , unless otherwise specified

**Static characteristics**

|                                  |               |  |      |       |      |            |
|----------------------------------|---------------|--|------|-------|------|------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-1mA$                          | -40  | -     | -    | V          |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=-150\mu A$                 | -2.0 | -3.0  | -4.0 |            |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=-32V, V_{GS}=0V, T_j=25^\circ C$       | -    | -0.05 | -1   | $\mu A$    |
|                                  |               | $V_{DS}=-32V, V_{GS}=0V, T_j=125^\circ C^{2)}$ | -    | -20   | -200 |            |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=-20V, V_{DS}=0V$                       | -    | -     | -100 | nA         |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=-10V, I_D=-80A$                        | -    | 5.7   | 7.7  | m $\Omega$ |
|                                  |               | $V_{GS}=-10V, I_D=-80A, \text{SMD version}$    | -    | 5.4   | 7.4  |            |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Dynamic characteristics<sup>2)</sup>**

|                              |              |   |   |      |      |    |
|------------------------------|--------------|---|---|------|------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0V, V_{DS}=-25V,$<br>$f=1MHz$                         | - | 4681 | 6085 | pF |
| Output capacitance           | $C_{oss}$    |   | - | 1520 | 2280 |    |
| Reverse transfer capacitance | $C_{rss}$    |   | - | 45   | 91   |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=-20V,$<br>$V_{GS}=-10V, I_D=-80A,$<br>$R_G=3.5\Omega$ | - | 25   | -    | ns |
| Rise time                    | $t_r$        |   | - | 15   | -    |    |
| Turn-off delay time          | $t_{d(off)}$ |   | - | 34   | -    |    |
| Fall time                    | $t_f$        |   | - | 41   | -    |    |

**Gate Charge Characteristics<sup>2)</sup>**

|                       |               |   |   |      |    |    |
|-----------------------|---------------|---|---|------|----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=-32V,$<br>$I_D=-80A,$<br>$V_{GS}=0$ to $-10V$ | - | 25   | 33 | nC |
| Gate to drain charge  | $Q_{gd}$      |   | - | 13   | 26 |    |
| Gate charge total     | $Q_g$         |   | - | 68   | 89 |    |
| Gate plateau voltage  | $V_{plateau}$ |   | - | -5.4 | -  | V  |

**Reverse Diode**

|  |               |  |   |    |      |    |
|--|---------------|--|---|----|------|----|
| Diode continuous forward current <sup>2)</sup> | $I_S$         | $T_C=25^\circ C$                               | - | -  | -80  | A  |
| Diode pulse current <sup>2)</sup>              | $I_{S,pulse}$ |  | - | -  | -320 |    |
| Diode forward voltage                          | $V_{SD}$      | $V_{GS}=0V, I_F=-80A,$<br>$T_j=25^\circ C$     | - | -1 | -1.3 | V  |
| Reverse recovery time <sup>2)</sup>            | $t_{rr}$      | $V_R=-20V, I_F=-50A,$<br>$di_F/dt=-100A/\mu s$ | - | 48 | -    | ns |
| Reverse recovery charge <sup>2)</sup>          | $Q_{rr}$      |  | - | 54 | -    | nC |

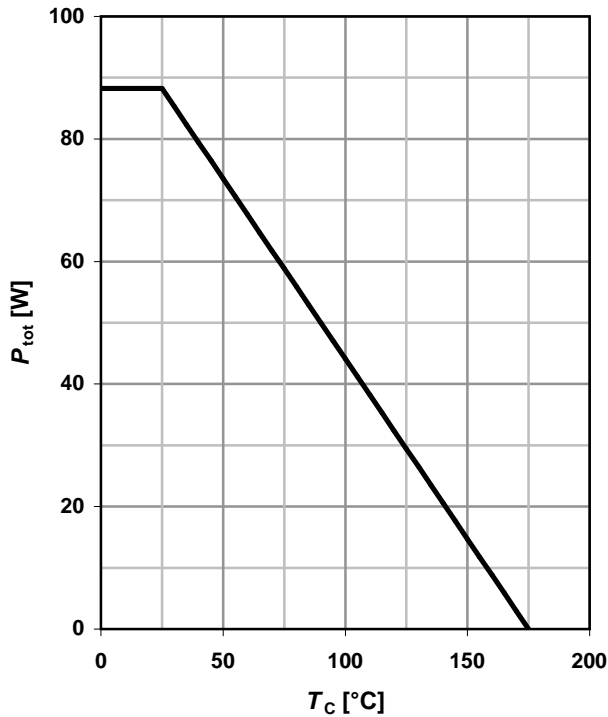
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 1.7K/W$  the chip is able to carry -88A at 25°C.

<sup>2)</sup> Defined by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

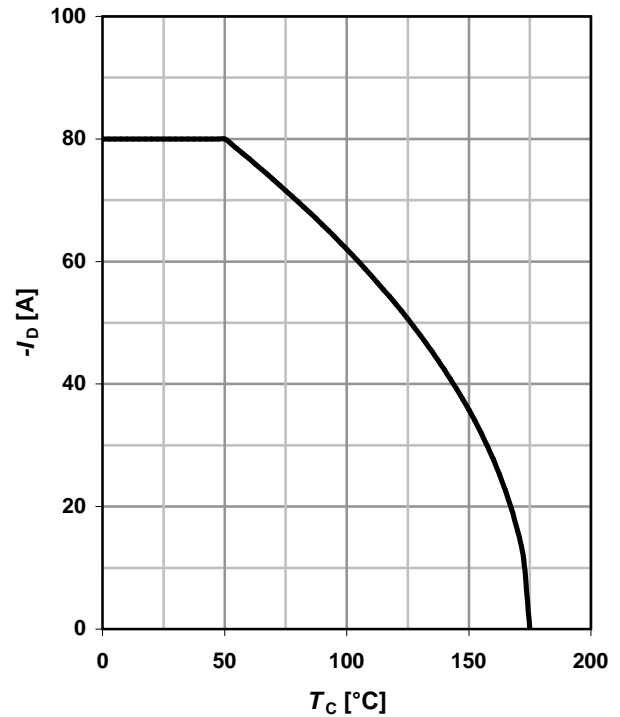
**1 Power dissipation**

$P_{tot} = f(T_C); V_{GS} \leq -6V$



**2 Drain current**

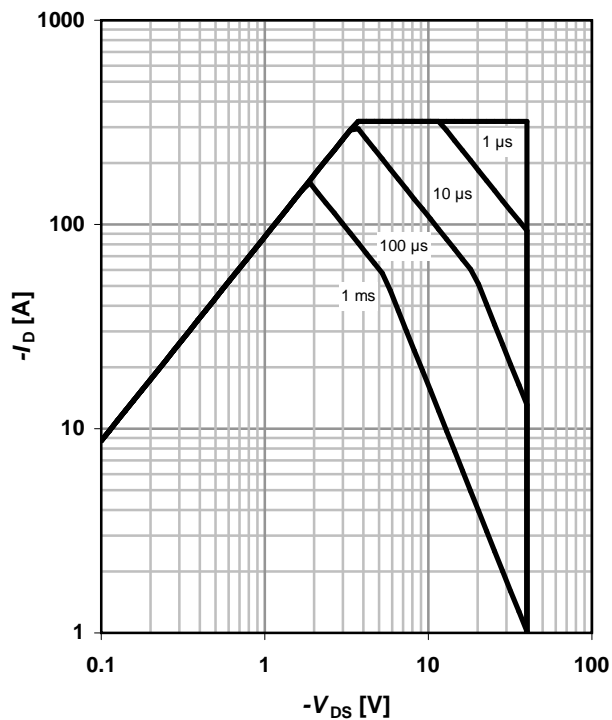
$I_D = f(T_C); V_{GS} \leq -6V; SMD$



**3 Safe operating area**

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0; SMD$

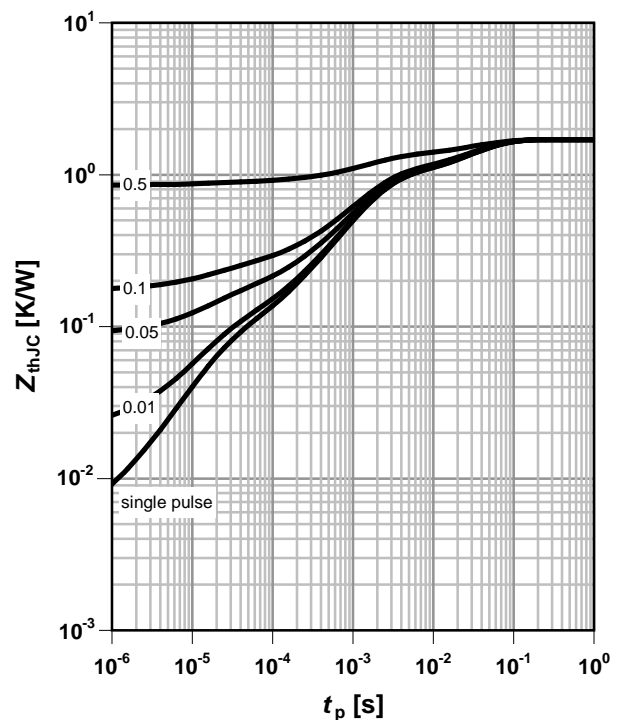
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

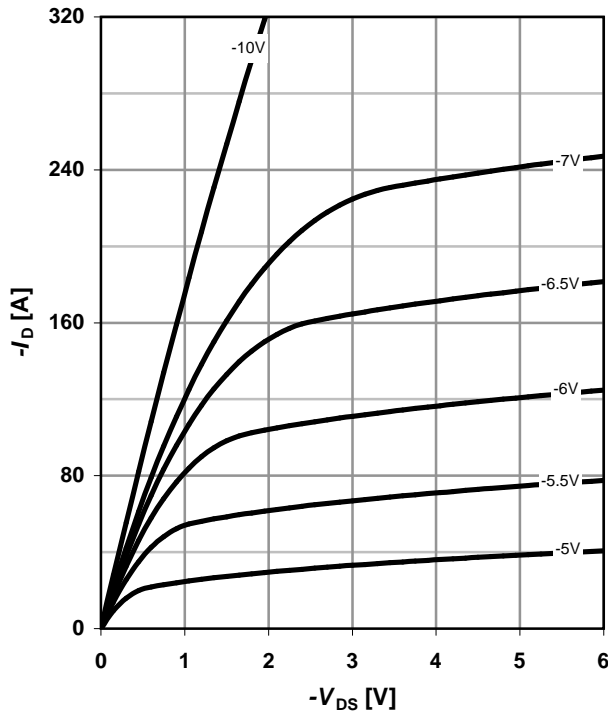
parameter:  $D = t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}; \text{SMD}$

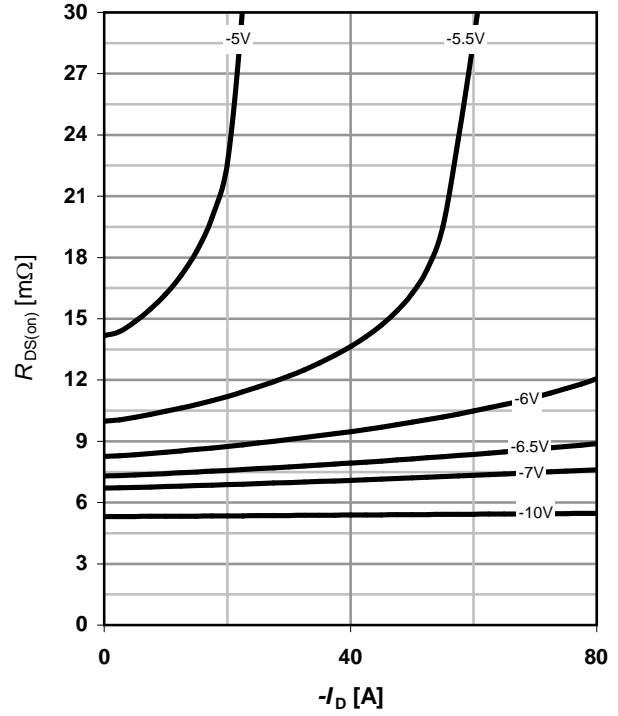
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}; \text{SMD}$

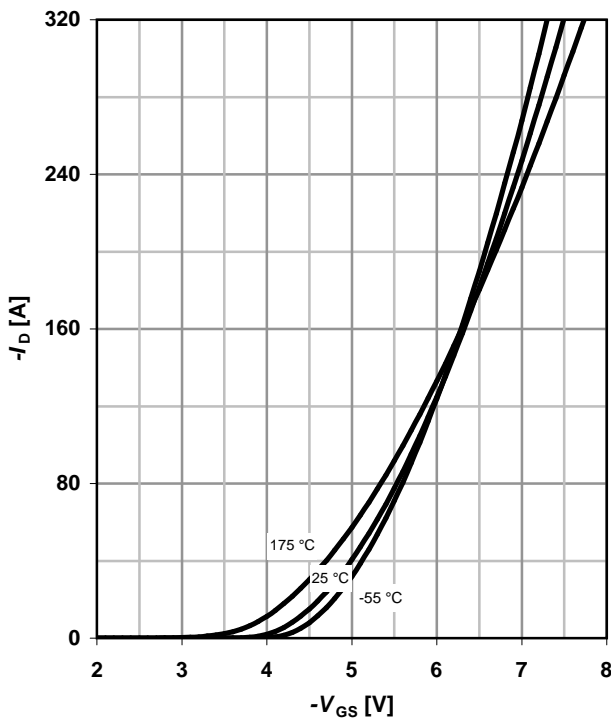
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

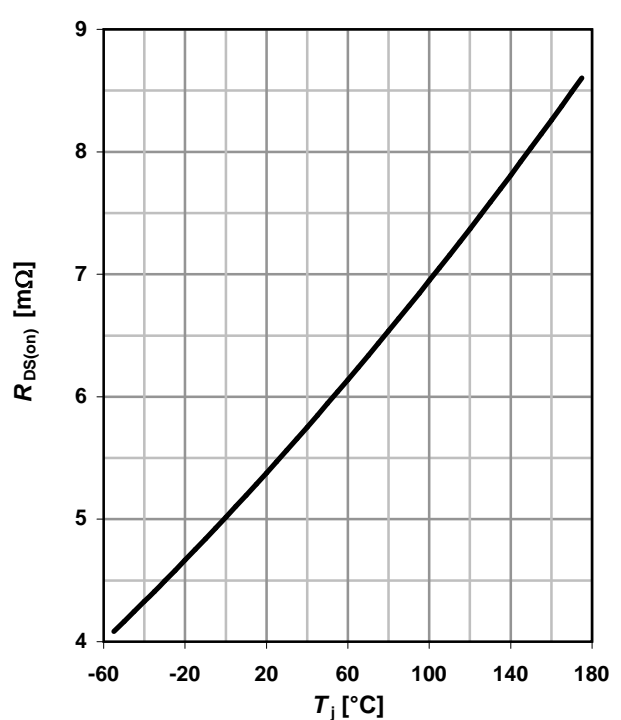
$I_D = f(V_{GS}); V_{DS} = -6V$

parameter:  $T_j$



**8 Typ. drain-source on-state resistance**

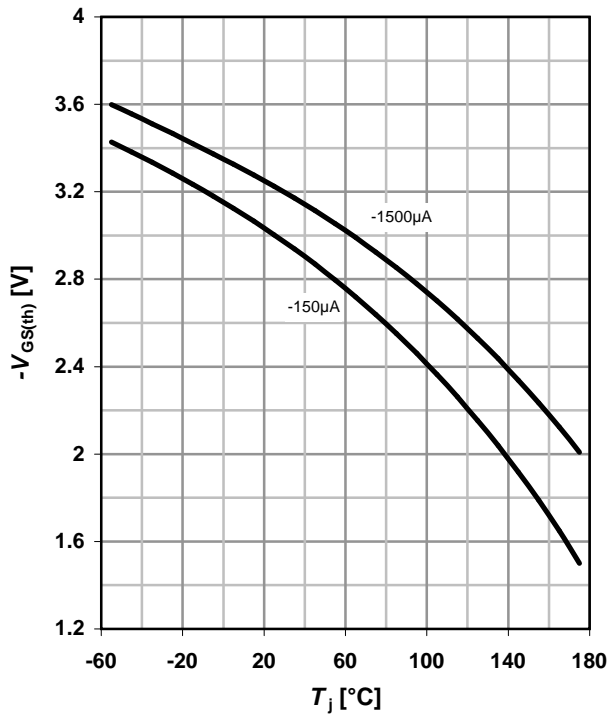
$R_{DS(on)} = f(T_j); I_D = -80\text{ A}; V_{GS} = -10\text{ V}; \text{SMD}$



**9 Typ. gate threshold voltage**

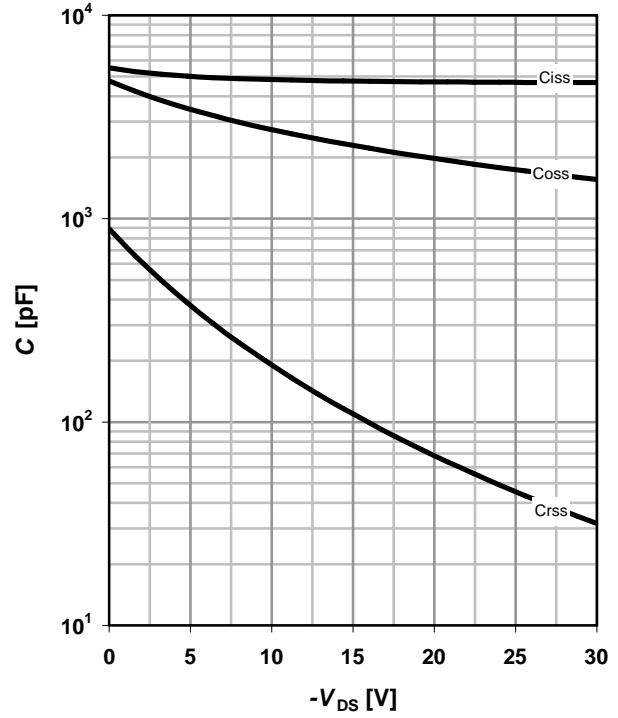
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**10 Typ. capacitances**

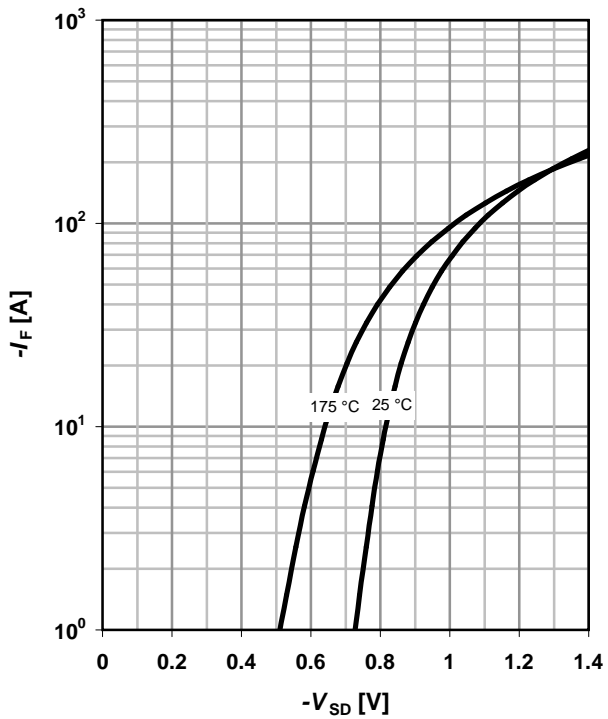
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



**11 Typical forward diode characteristics**

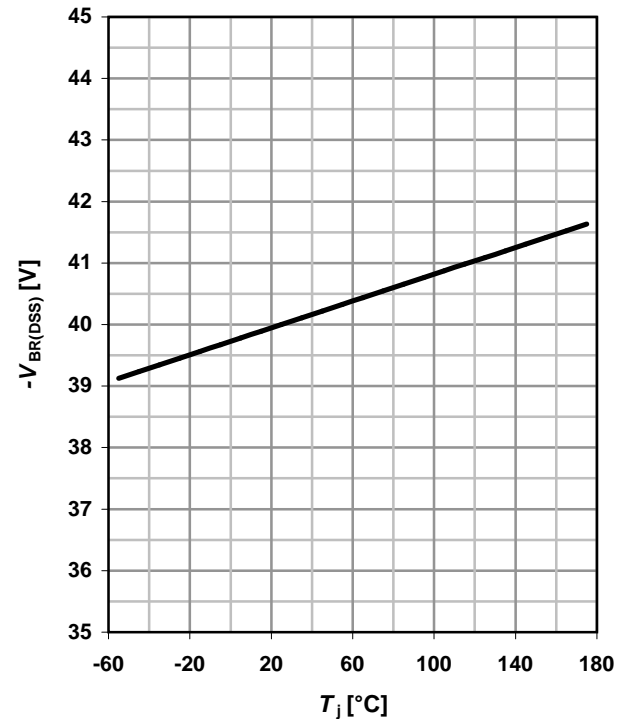
$I_F = f(V_{SD})$

parameter:  $T_j$



**12 Drain-source breakdown voltage**

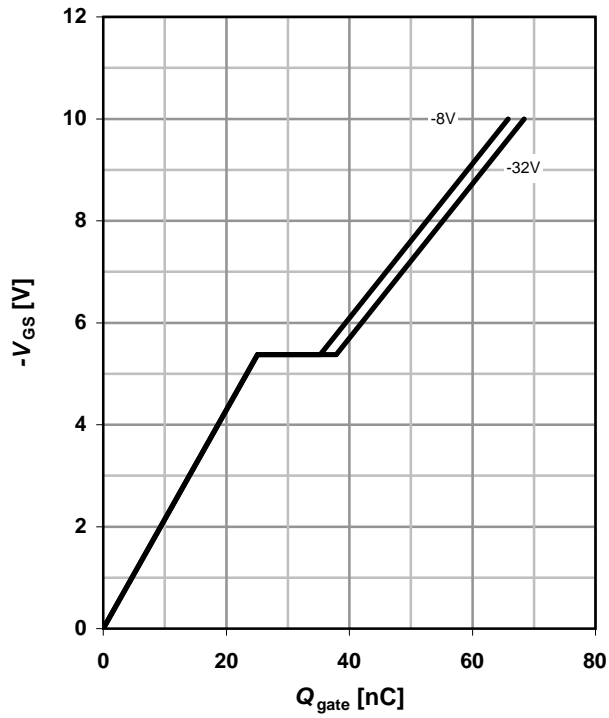
$V_{BR(DSS)} = f(T_j); I_D = -1 mA$



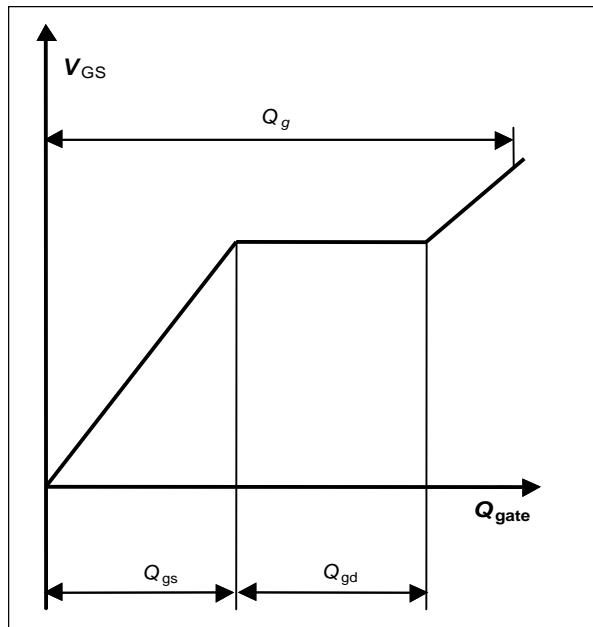
15 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = -80 \text{ A pulsed}$

parameter:  $V_{DD}$



16 Gate charge waveforms



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## Revision History

| Version | Date       | Changes                   |
|---------|------------|---------------------------|
| 0.1     | 29.01.2010 | Initial Target Data Sheet |
| 1.0     | 10.02.2011 | Final Data Sheet          |

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